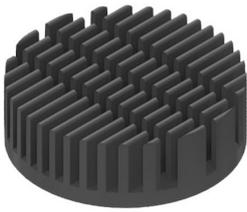


Data sheet Product ICKLEDR50.8x16.5G_



Heatsinks and active heatsinks for processors>Heatsinks for LEDs
 Ø 50,8 x 16,5 mm, for IC design LED

Features

diameter:	50.8 mm
way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
height:	16.51 mm
plate thickness:	4 mm
thermal resistance:	10.49 - 2 K/W
dissipation loss:	10.9 W
surface:	black anodised

Technical Drawing

